

Title (en)

INTERCONNECT SYSTEM FOR A PRINTED CIRCUIT BOARD

Title (de)

VERBINDUNGSSYSTEM FÜR PLATINE MIT EINER GEDRUCKTEN SCHALTUNG

Title (fr)

SYSTÈME DE LIAISON POUR UNE CARTE DE CIRCUIT IMPRIMÉ

Publication

EP 2425498 B1 20140326 (DE)

Application

EP 10718885 A 20100430

Priority

- EP 2010002664 W 20100430
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Abstract (en)

[origin: WO2010124878A1] The invention relates to an interconnect system for a printed circuit board (1) having at least one first connecting element (2) and one second connecting element (3). The first connecting element (2) is formed of a first conductive film (21) and a second conductive film (22). The first conductive film (21) is printed on a first side (A) of the printed circuit board (1), whereas the second conductive film (22) is printed on a second side (B) of the printed circuit board (1). The invention provides that the second connecting element (3) is comprised of a first spring (31) and a second spring (32). The first spring (31) and the second spring (32) are constructed such that with the first spring (31) exerting pressure on the first conductive film (21), and the second spring (32) exerting pressure on the second conductive film (22), a respective galvanic contact of spring (31, 32) and conductive film (21, 22) is made.

IPC 8 full level

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CPC (source: EP ES)

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